PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hsien-Wei Chen	04/27/2007
Shih-Hsun Hsu	04/30/2007
Hsueh-Chung Chen	05/15/2007

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.			
Street Address:	No. 8, Li-Hsin Rd. 6			
Internal Address:	Science-Based Industrial Park			
City:	Hsin-Chu			
State/Country:	TAIWAN			
Postal Code:	300-77, R.O.C.			

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12426995

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 252011-4351

NAME OF SUBMITTER: Daniel R. McClure

PATENT REEL: 022570 FRAME: 0499 OP \$40.00 12426995

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Total Attachments: 2 source=00899686#page1.tif source=00899686#page2.tif

> PATENT REEL: 022570 FRAME: 0500

ASSEGNMENT

WHEREAS, Hsien-Wei CHEN, Shih-Hsun HSU and Hsueh-Chung CHEN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

	ICONDUCTOR		, , 					
Filed:					Serie	al No.		
Executed or	: April 27	2007;	April	30,	2007ටand	May	15,	2007

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MA' CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assigner further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignees expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

T5MC2004-0375/0503-A32467US

PATENT REEL: 022570 FRAME: 0501 IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Hsien-Wei CHEN

4/27, 2007

Shin-Houn Hour Hou

14/40, 2007

Hsueh-Chung CHEN Chung CHEN

Date: 14 15 200)

TSMC2004-0375/0503-A32467US

PATENT REEL: 022570 FRAME: 0502

RECORDED: 04/21/2009